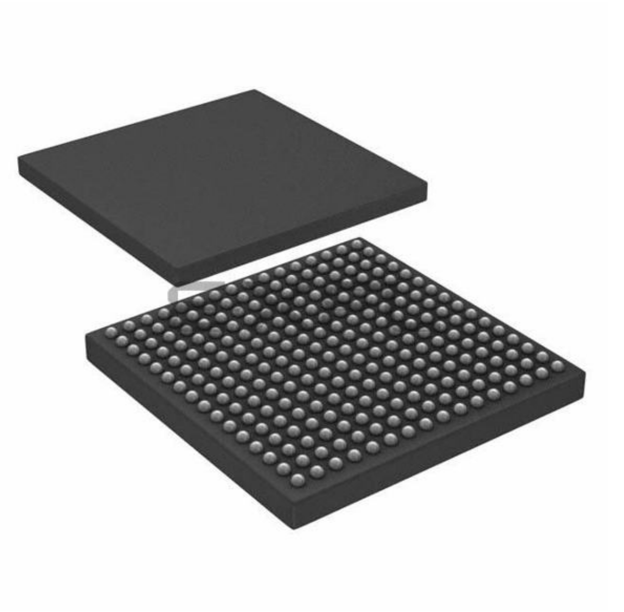
Microsemi Corporation - AX125-1FG256I Datasheet



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Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	2016
Number of Logic Elements/Cells	-
Total RAM Bits	18432
Number of I/O	138
Number of Gates	125000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 85°C (TA)
Package / Case	256-LBGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/microsemi/ax125-1fg256i

Ordering Information

AX1000 – 1 FG G 896 I

Application
Blank = Commercial (0 to +70° C)
PP = Pre-Production
I = Industrial (-40 to +85° C)
M = Military (-55 to +125° C)

Package Lead Count

Lead-Free Packaging
Blank = Standard Packaging
G= RoHS-Compliant Packaging

Package Type
BG = Ball Grid Array (1.27mm pitch)
FG = Fine Ball Grid Array (1.0mm pitch)
PQ = Plastic Quad Flat Pack (0.5mm pitch)
CQ = Ceramic Quad Flat Pack (0.5mm pitch)
CG = Ceramic Column Grid Array

Speed Grade
Blank = Standard Speed
1 = Approximately 15% Faster than Standard
2 = Approximately 25% Faster than Standard

Part Number
AX125 = 125,000 Equivalent System Gates
AX250 = 250,000 Equivalent System Gates
AX500 = 500,000 Equivalent System Gates
AX1000 = 1,000,000 Equivalent System Gates
AX2000 = 2,000,000 Equivalent System Gates

Device Resources

User I/Os (Including Clock Buffers)					
Package	**AX125**	**AX250**	**AX500**	**AX1000**	**AX2000**
PQ208	–	115	115	–	–
CQ208	–	115	115	–	–
CQ256	–	–	–	–	136
FG256	138	138	–	–	–
FG324	168	–	–	–	–
CQ352	–	198	198	198	198
FG484	–	248	317	317	–
CG624	–	–	–	418	418
FG676	–	–	336	418	–
BG729	–	–	–	516	–
FG896	–	–	–	516	586
FG1152	–	–	–	–	684

Note: *The FG256, FG324, and FG484 are footprint compatible with one another. The FG676, FG896, and FG1152 are also footprint compatible with one another.*

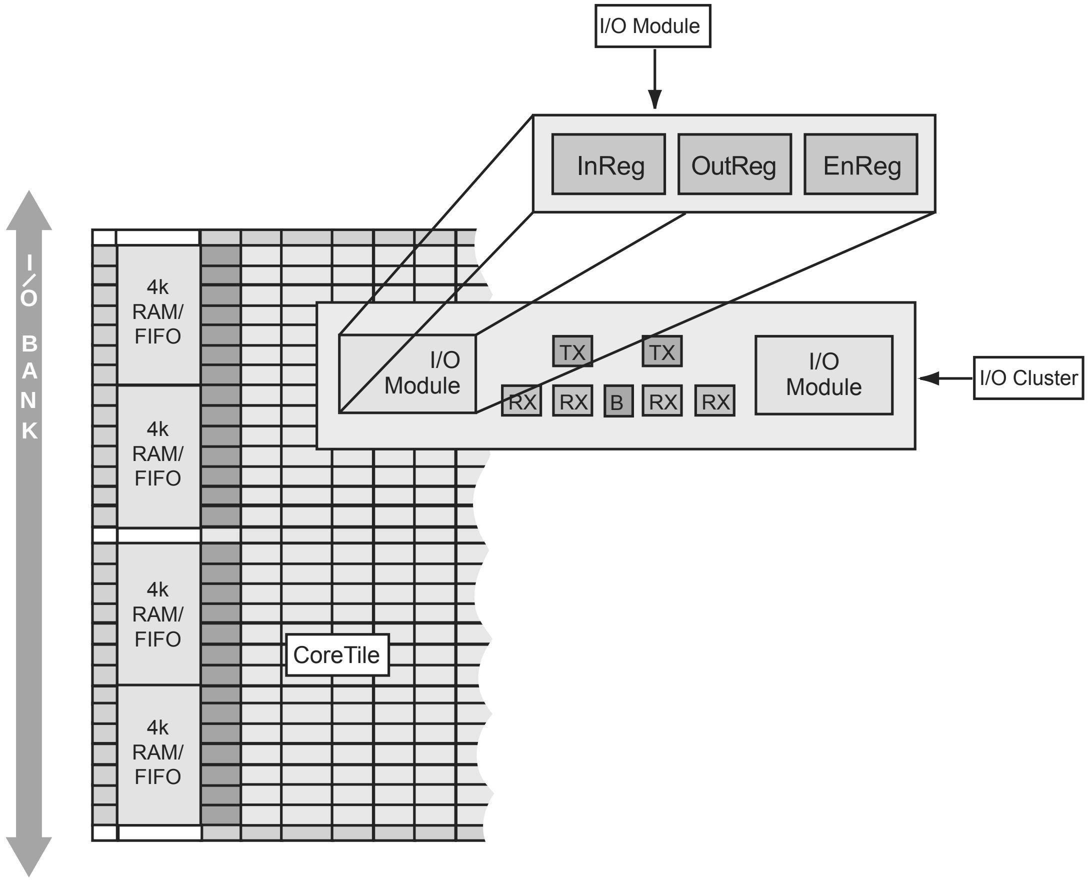

Figure 1-7 • **I/O Cluster Arrangement**

Routing

The AX hierarchical routing structure ties the logic modules, the embedded memory blocks, and the I/O modules together (Figure 1-8 on page 1-6). At the lowest level, in and between SuperClusters, there are three local routing structures: FastConnect, DirectConnect, and CarryConnect routing. DirectConnects provide the highest performance routing inside the SuperClusters by connecting a C-cell to the adjacent R-cell. DirectConnects do not require an antifuse to make the connection and achieve a signal propagation time of less than 0.1 ns.

FastConnects provide high-performance, horizontal routing inside the SuperCluster and vertical routing to the SuperCluster immediately below it. Only one programmable connection is used in a FastConnect path, delivering a maximum routing delay of 0.4 ns.

CarryConnects are used for routing carry logic between adjacent SuperClusters. They connect the FCO output of one two-bit, C-cell carry logic to the FCI input of the two-bit, C-cell carry logic of the SuperCluster below it. CarryConnects do not require an antifuse to make the connection and achieve a signal propagation time of less than 0.1 ns.

The next level contains the core tile routing. Over the SuperClusters within a core tile, both vertical and horizontal tracks run across rows or columns, respectively. At the chip level, vertical and horizontal tracks extend across the full length of the device, both north-to-south and east-to-west. These tracks are composed of highway routing that extend the entire length of the device (segmented at core tile boundaries) as well as segmented routing of varying lengths.

User I/Os[2]

Introduction

The Axcelerator family features a flexible I/O structure, supporting a range of mixed voltages (1.5 V, 1.8 V, 2.5 V, and 3.3 V) with its bank-selectable I/Os. Table 2-8 on page 2-12 contains the I/O standards supported by the Axcelerator family, and Table 2-10 on page 2-12 compares the features of the different I/O standards.

Each I/O provides programmable slew rates, drive strengths, and weak pull-up and weak pull-down circuits. The slew rate setting is effective for both rising and falling edges.

I/O standards, except 3.3 V PCI and 3.3 V PCI-X, are capable of hot insertion. 3.3 V PCI and 3.3 V PCI-X are 5 V tolerant with the aid of an external resistor.

The input buffer has an optional user-configurable delay element. The element can reduce or eliminate the hold time requirement for input signals registered within the I/O cell. The value for the delay is set on a bank-wide basis. Note that the delay WILL be a function of process variations as well as temperature and voltage changes.

Each I/O includes three registers: an input (InReg), an output (OutReg), and an enable register (EnReg). I/Os are organized into banks, and there are eight banks per device—two per side (Figure 2-6 on page 2-18). Each I/O bank has a common VCCI, the supply voltage for its I/Os.

For voltage-referenced I/Os, each bank also has a common reference-voltage bus, VREF. While VREF must have a common voltage for an entire I/O bank, its location is user-selectable. In other words, any user I/O in the bank can be selected to be a VREF.

The location of the VREF pin should be selected according to the following rules:

- Any pin that is assigned as a VREF can control a maximum of eight user I/O pad locations in each direction (16 total maximum) within the same I/O bank.
- I/O pad locations listed as no connects are counted as part of the 16 maximum. In many cases, this leads to fewer than eight user I/O package pins in each direction being controlled by a VREF pin.
- Dedicated I/O pins such as GND and VCCI are counted as part of the 16.
- The two user I/O pads immediately adjacent on each side of the VREF pin (four in total) may only be used as inputs. The exception is when there is a VCCI/GND pair separating the VREF pin and the user I/O pad location.
- The user does not need to assign VREF pins for OUTBUF and TRIBUF. VREF pins are needed only for input and bidirectional I/Os.

The differential amplifier supply voltage VCCDA should be connected to 3.3 V.

A user can gain access to the various I/O standards in three ways:

- Instantiate specific library macros that represent the desired specific standard.
- Use generic I/O macros and then use Designer’s PinEditor to specify the desired I/O standards (please note that this is not applicable to differential standards).
- A combination of the first two methods.

Refer to the *I/O Features in Axcelerator Family Devices* application note and the *Antifuse Macro Library Guide* for more details.

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[2] *Do not use an external resister to pull the I/O above V_{CCI} for a higher logic “1” voltage level. The desired higher logic “1” voltage level will be degraded due to a small I/O current, which exists when the I/O is pulled up above V_{CCI}.*

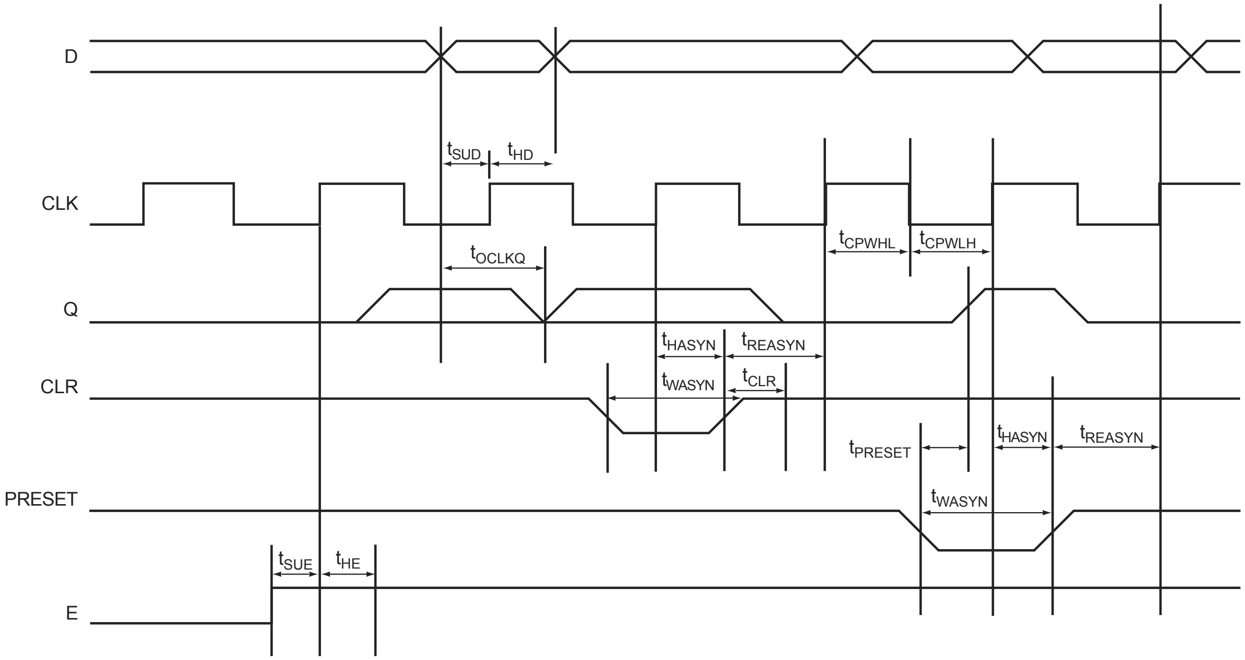


Figure 2-13 • **Output Register Timing Characteristics**

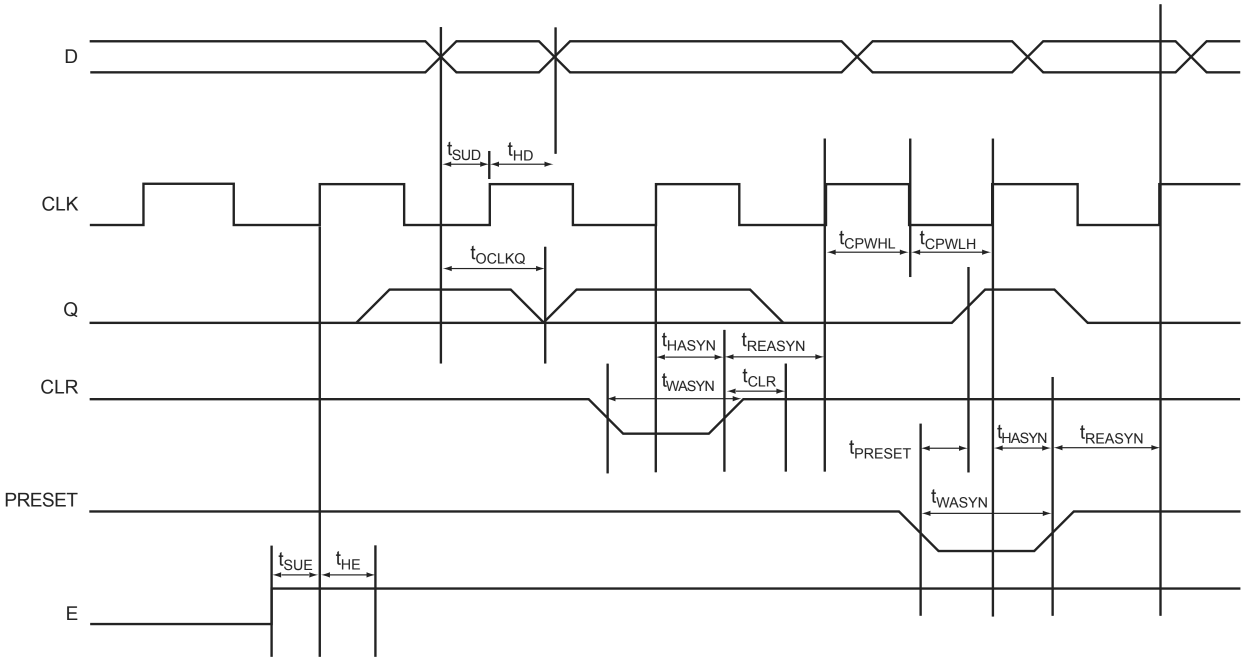


Figure 2-14 • **Output Enable Register Timing Characteristics**

Timing Characteristics

Table 2-28 **• 1.8V LVCMOS I/O Module**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 1.7 V, TJ = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
LVCMOS18 Output Module Timing								
t_{DP}	Input Buffer		3.26		3.71		4.37	ns
t_{PY}	Output Buffer		4.55		5.18		6.09	ns
t_{ENZL}	Enable to Pad Delay through the Output Buffer—Z to Low		2.82		2.83		2.84	ns
t_{ENZH}	Enable to Pad Delay through the Output Buffer—Z to High		3.43		3.45		3.46	ns
t_{ENLZ}	Enable to Pad Delay through the Output Buffer—Low to Z		6.01		6.85		8.05	ns
t_{ENHZ}	Enable to Pad Delay through the Output Buffer—High to Z		6.73		7.67		9.01	ns
t_{IOCLKQ}	Sequential Clock-to-Q for the I/O Input Register		0.67		0.77		0.90	ns
t_{IOCLKY}	Clock-to-output Y for the I/O Output Register and the I/O Enable Register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

3.3 V PCI, 3.3 V PCI-X

Peripheral Component Interface for 3.3 V standard specifies support for both 33 MHz and 66 MHz PCI bus applications. It uses an LVTTL input buffer and a push-pull output buffer. The input and output buffers are 5 V tolerant with the aid of external components. Axcelerator 3.3 V PCI and 3.3 V PCI-X buffers are compliant with the PCI Local Bus Specification Rev. 2.1.

The PCI Compliance Specification requires the clamp diodes to be able to withstand for 11 ns, –3.5 V in undershoot, and 7.1 V in overshoot.

Table 2-33 **• DC Input and Output Levels**

	VIL		VIH		VOL	VOH	IOL	IOH
	Min., V	**Max., V**	**Min., V**	**Max., V**	**Max., V**	**Min., V**	**mA**	**mA**
PCI	–0.3	0.3 VCCI	0.5 VCCI	VCCI + 0.5	(per PCI specification)			
PCI-X	–0.5	0.35 VCCI	0.5 VCCI	VCCI + 0.5	(per PCI specification)			

AC Loadings

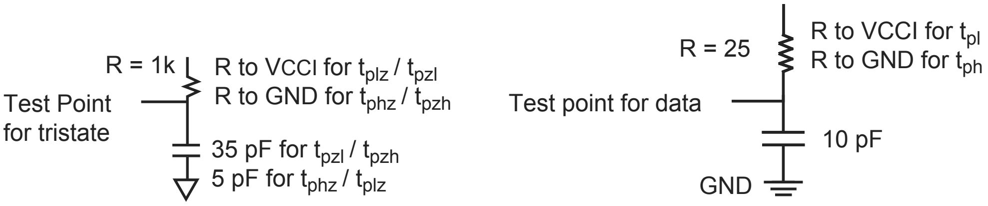


Figure 2-18 **• AC Test Loads**

Table 2-34 **• AC Waveforms, Measuring Points, and Capacitive Loads**

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ) (V)	C_{load} (pF)
(Per PCI Spec and PCI-X Spec)			N/A	10

*Note: * Measuring Point = VTRIP*

Buffer Module

Introduction

An additional resource inside each SuperCluster is the Buffer (B) module (Figure 1-4 on page 1-3). When a fanout constraint is applied to a design, the synthesis tool inserts buffers as needed. The buffer module has been added to the AX architecture to avoid logic duplication resulting from the hard fanout constraints. The router utilizes this logic resource to save area and reduce loading and delays on medium-to-high-fanout nets.

Timing Models and Waveforms

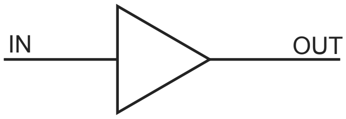


Figure 2-33 • **Buffer Module Timing Model**

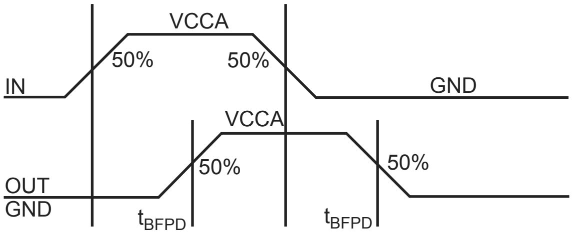


Figure 2-34 • **Buffer Module Waveform**

Timing Characteristics

Table 2-64 **• Buffer Module**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
Buffer Module Propagation Delays								
t_{BFPD}	Any input to output Y		0.12		0.14		0.16	ns

Vertical and Horizontal Routing

Vertical and Horizontal Tracks provide both local and long distance routing (Figure 2-37 on page 2-62). These tracks are composed of both short-distance, segmented routing and across-chip routing tracks (segmented at core tile boundaries). The short-distance, segmented routing resources can be concatenated through antifuse connections to build longer routing tracks.

These short-distance routing tracks can be used within and between SuperClusters or between modules of non-adjacent SuperClusters. They can be connected to the Output Tracks and to any logic module input (R-cell, C-cell, Buffer, and TX module).

The across-chip horizontal and vertical routing provides long-distance routing resources. These resources interface with the rest of the routing structures through the RX and TX modules (Figure 2-37). The RX module is used to drive signals from the across-chip horizontal and vertical routing to the Output Tracks within the SuperCluster. The TX module is used to drive vertical and horizontal across-chip routing from either short-distance horizontal tracks or from Output Tracks. The TX module can also be used to drive signals from vertical across-chip tracks to horizontal across-chip tracks and vice versa.

Figure 2-36 • **FastConnect Routing**

Figure 2-37 • **Horizontal and Vertical Tracks**

Table 2-72 • **AX500 Dedicated (Hardwired) Array Clock Networks**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
Dedicated (Hardwired) Array Clock Networks								
t_{HCKL}	Input Low to High		2.35		2.68		3.15	ns
t_{HCKH}	Input High to Low		2.44		2.79		3.27	ns
t_{HPWH}	Minimum Pulse Width High	0.58		0.65		0.77		ns
t_{HPWL}	Minimum Pulse Width Low	0.52		0.59		0.69		ns
t_{HCKSW}	Maximum Skew		0.06		0.07		0.08	ns
t_{HP}	Minimum Period	1.15		1.31		1.54		ns
t_{HMAX}	Maximum Frequency		870		763		649	MHz

Table 2-73 • **AX1000 Dedicated (Hardwired) Array Clock Networks**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
Dedicated (Hardwired) Array Clock Networks								
t_{HCKL}	Input Low to High		3.02		3.44		4.05	ns
t_{HCKH}	Input High to Low		3.03		3.46		4.06	ns
t_{HPWH}	Minimum Pulse Width High	0.58		0.65		0.77		ns
t_{HPWL}	Minimum Pulse Width Low	0.52		0.59		0.69		ns
t_{HCKSW}	Maximum Skew		0.06		0.07		0.08	ns
t_{HP}	Minimum Period	1.15		1.31		1.54		ns
t_{HMAX}	Maximum Frequency		870		763		649	MHz

Table 2-74 • **AX2000 Dedicated (Hardwired) Array Clock Networks**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
Dedicated (Hardwired) Array Clock Networks								
t_{HCKL}	Input Low to High		3.02		3.44		4.05	ns
t_{HCKH}	Input High to Low		3.03		3.46		4.06	ns
t_{HPWH}	Minimum Pulse Width High	0.58		0.65		0.77		ns
t_{HPWL}	Minimum Pulse Width Low	0.52		0.59		0.69		ns
t_{HCKSW}	Maximum Skew		0.06		0.07		0.08	ns
t_{HP}	Minimum Period	1.15		1.31		1.54		ns
t_{HMAX}	Maximum Frequency		870		763		649	MHz

The ClockTileDist Cluster contains an HCLKMux (HM) module for each of the four HCLK trees and a CLKMux (CM) module for each of the CLK trees. The HCLK branches then propagate horizontally through the middle of the core tile to HCLKColDist (HD) modules in every SuperCluster column. The CLK branches propagate vertically through the center of the core tile to CLKRowDist (RD) modules in every SuperCluster row. Together, the HCLK and CLK branches provide for a low-skew global fanout within the core tile (Figure 2-40 and Figure 2-41).

***Figure 2-40* • CTD, CD, and HD Module Layout**

***Figure 2-41* • HCLK and CLK Distribution within a Core Tile**

Table 2-93 • Sixteen RAM Blocks Cascaded
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
Write Mode								
t_{WDASU}	Write Data Setup vs. WCLK		16.54		18.84		22.15	ns
t_{WDAHD}	Write Data Hold vs. WCLK		0.00		0.00		0.00	ns
t_{WADSU}	Write Address Setup vs. WCLK		16.54		18.84		22.15	ns
t_{WADHD}	Write Address Hold vs. WCLK		0.00		0.00		0.00	ns
t_{WENSU}	Write Enable Setup vs. WCLK		16.54		18.84		22.15	ns
t_{WENHD}	Write Enable Hold vs. WCLK		0.00		0.00		0.00	ns
t_{WCKH}	WCLK Minimum High Pulse Width	0.75		0.75		0.75		ns
t_{WCLK}	WCLK Minimum Low Pulse Width	13.40		13.40		13.40		ns
t_{WCKP}	WCLK Minimum Period	14.15		14.15		14.15		ns
Read Mode								
t_{RADSU}	Read Address Setup vs. RCLK		18.13		20.65		24.27	ns
t_{RADHD}	Read Address Hold vs. RCLK		0.00		0.00		0.00	ns
t_{RENSU}	Read Enable Setup vs. RCLK		18.13		20.65		24.27	ns
t_{RENHD}	Read Enable Hold vs. RCLK		0.00		0.00		0.00	ns
$t_{RCK2RD1}$	RCLK-To-OUT (Pipelined)		12.08		13.76		16.17	ns
$t_{RCK2RD2}$	RCLK-To-OUT (Non-Pipelined)		12.83		14.62		17.18	ns
t_{RCLKH}	RCLK Minimum High Pulse Width	0.73		0.73		0.73		ns
t_{RCLKL}	RCLK Minimum Low Pulse Width	14.41		14.41		14.41		ns
t_{RCKP}	RCLK Minimum Period	15.14		15.14		15.14		ns

Note: Timing data for these sixteen cascaded RAM blocks uses a depth of 65,536. For all other combinations, use Microsemi's timing software.

FIFO

Every memory block has its own embedded FIFO controller. Each FIFO block has one read port and one write port. This embedded FIFO controller uses no internal FPGA logic and features:

- Glitch-free FIFO Flags
- Gray-code address counters/pointers to prevent metastability problems
- Overflow and underflow control

Both ports are configurable in various sizes from 4k x 1 to 128 x 36, similar to the RAM block size. Each port is fully synchronous.

Read and write operations can be completely independent. Data on the appropriate WD pins are written to the FIFO on every active WCLK edge as long as WEN is high. Data is read from the FIFO and output on the appropriate RD pins on every active RCLK edge as long as REN is asserted.

The FIFO block offers programmable almost-empty (AEMPTY) and almost-full (AFULL) flags as well as EMPTY and FULL flags (Figure 2-61):

- The FULL flag is synchronous to WCLK. It allows the FIFO to inhibit writing when full.
- The EMPTY flag is synchronous to RCLK. It allows the FIFO to inhibit reading at the empty condition.

Gray code counters are used to prevent metastability problems associated with flag logic. The depth of the FIFO is dependent on the data width and the number of memory blocks used to create the FIFO. The write operations to the FIFO are synchronous with respect to the WCLK, and the read operations are synchronous with respect to the RCLK.

The FIFO block may be reset to the empty state.

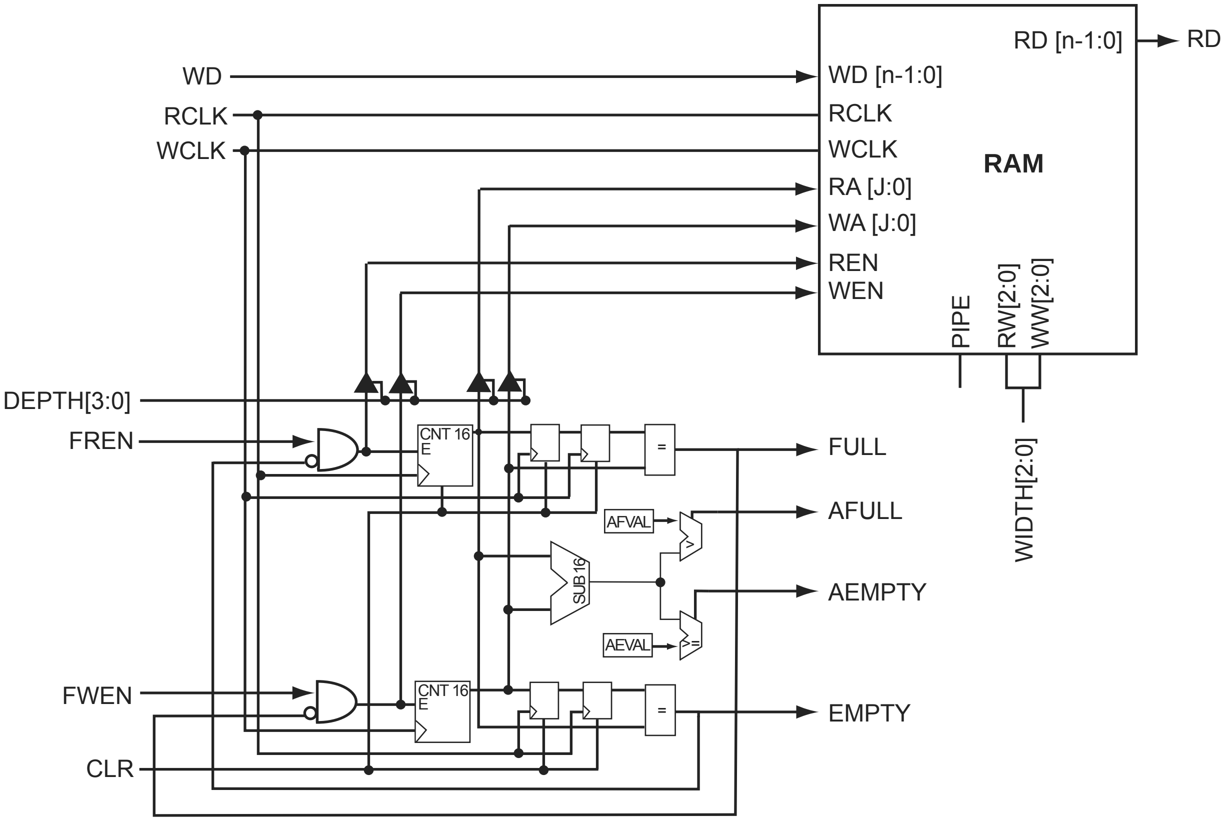


Figure 2-61 • **Axcelerator RAM with Embedded FIFO Controller**

Timing Characteristics

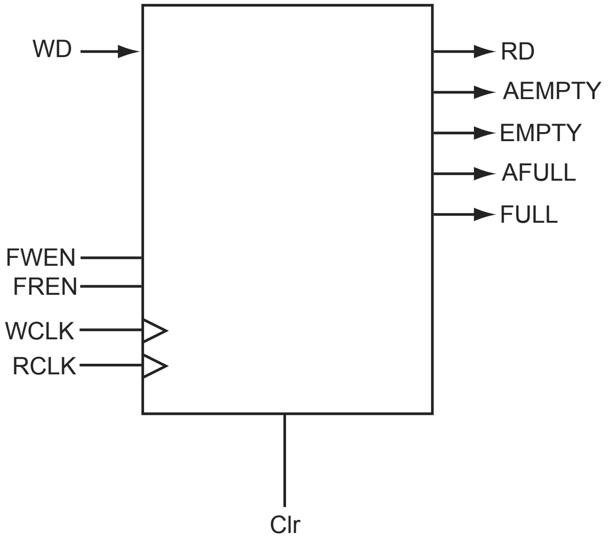


Figure 2-66 • **FIFO Model**

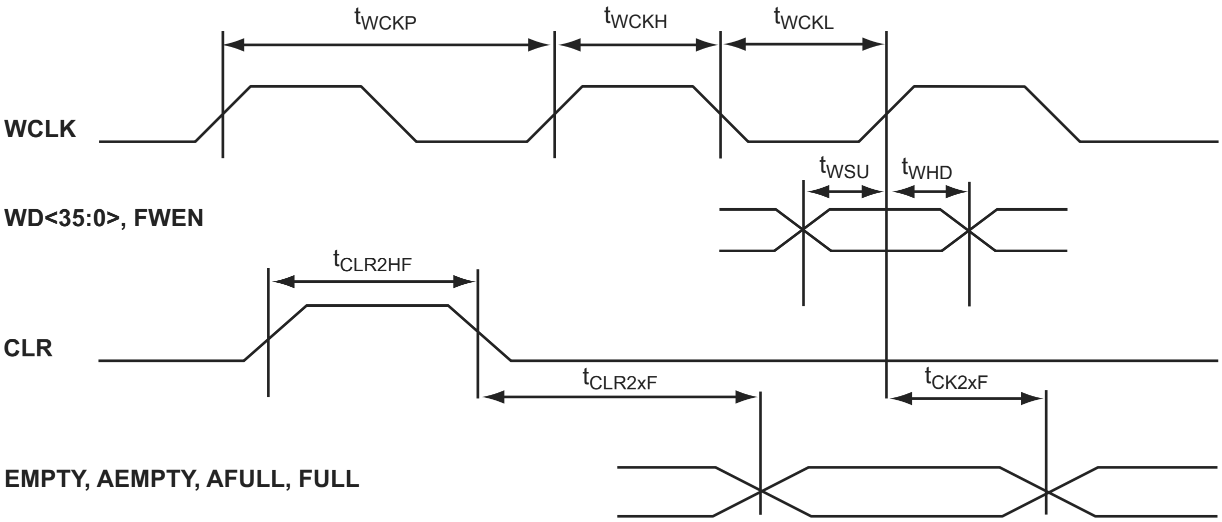
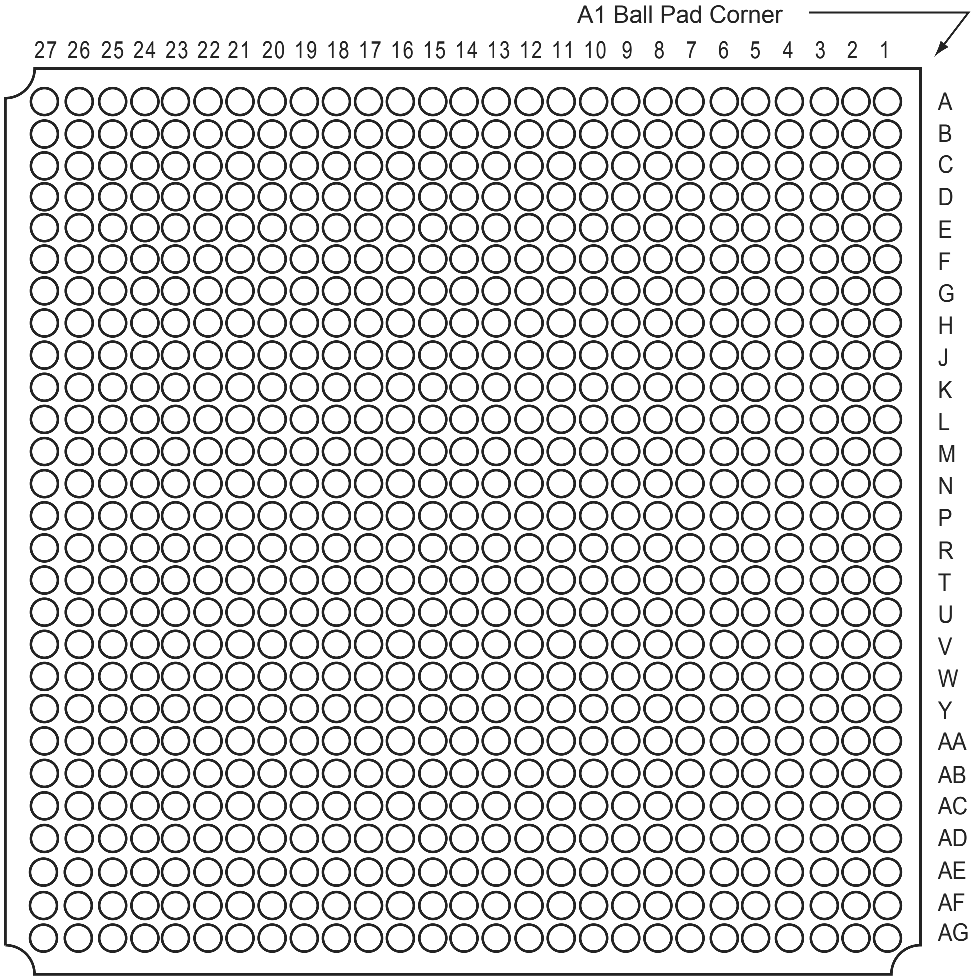


Figure 2-67 • **FIFO Write Timing**

3 – Package Pin Assignments

BG729



Note

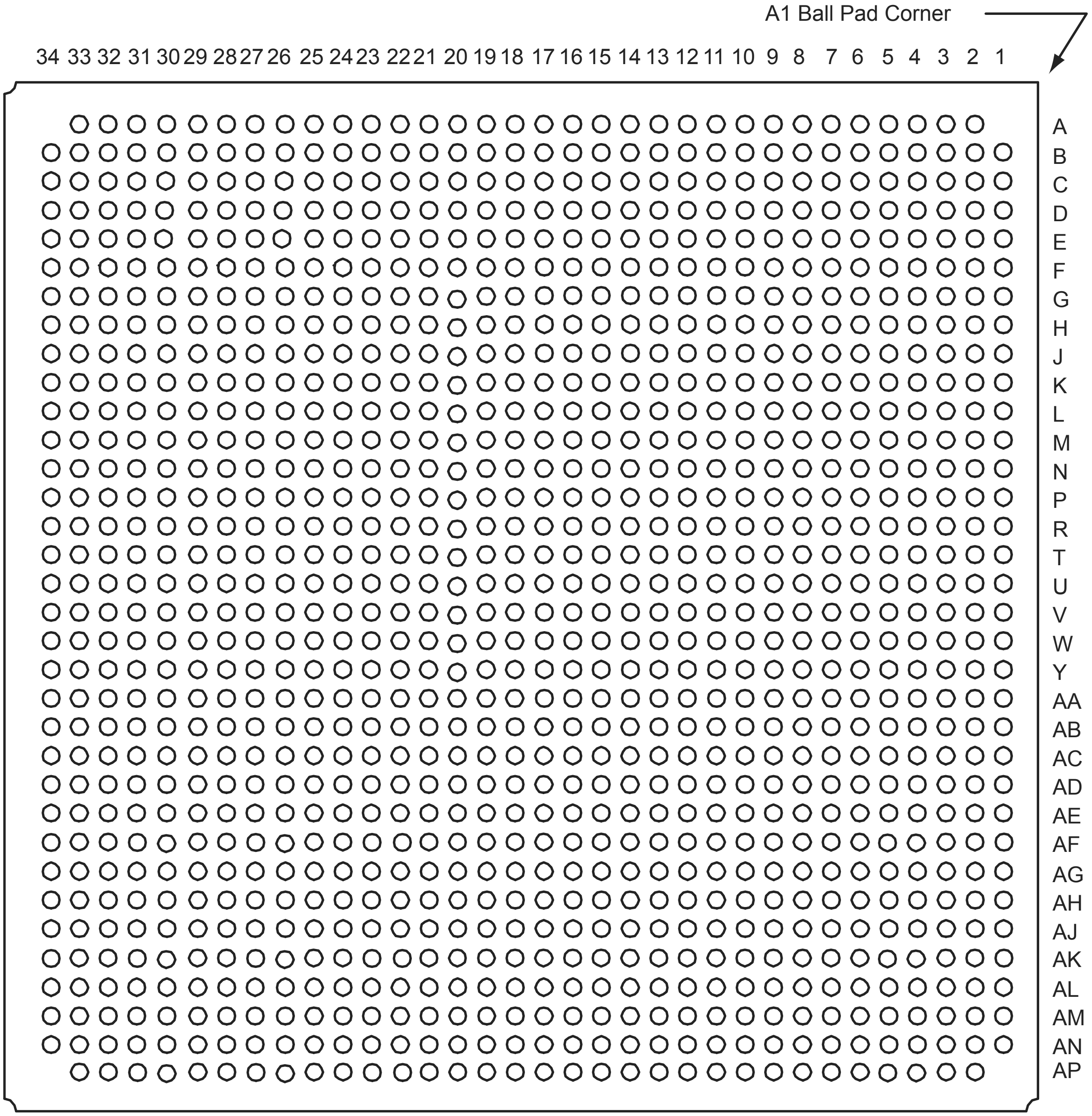
For Package Manufacturing and Environmental information, visit Resource center at http://www.microsemi.com/soc/products/rescenter/package/index.html.

FG484	
AX250 Function	**Pin Number**
IO104PB6F6	N4
IO105NB6F6	M5
IO105PB6F6	N5
IO106NB6F6	M3
IO106PB6F6	N3
Bank 7	
IO107NB7F7	M2
IO107PB7F7	N1
IO108NB7F7	L3
IO108PB7F7	L2
IO109NB7F7	K2
IO109PB7F7	K1
IO110NB7F7	K5
IO110PB7F7	L5
IO111NB7F7	K6
IO111PB7F7	L6
IO112NB7F7	K4
IO112PB7F7	K3
IO113NB7F7	K7
IO113PB7F7	L7
IO114NB7F7	H1
IO114PB7F7	J1
IO115NB7F7	H2
IO115PB7F7	J2
IO116NB7F7	H4
IO116PB7F7	J4
IO117NB7F7	H5
IO117PB7F7	J5
IO118NB7F7	F2
IO118PB7F7	G2
IO119NB7F7	H6
IO119PB7F7	J6
IO120NB7F7	F1
IO120PB7F7	G1
IO121NB7F7	F4
IO121PB7F7	G4

FG484	
AX250 Function	**Pin Number**
IO122NB7F7	G5
IO122PB7F7	G6
IO123NB7F7	F5
IO123PB7F7	E4
Dedicated I/O	
VCCDA	H7
GND	A1
GND	A11
GND	A12
GND	A2
GND	A21
GND	A22
GND	AA1
GND	AA2
GND	AA21
GND	AA22
GND	AB1
GND	AB11
GND	AB12
GND	AB2
GND	AB21
GND	AB22
GND	B1
GND	B2
GND	B21
GND	B22
GND	C20
GND	C3
GND	D19
GND	D4
GND	E18
GND	E5
GND	G18
GND	H15
GND	H8
GND	J14

FG484	
AX250 Function	**Pin Number**
GND	J9
GND	K10
GND	K11
GND	K12
GND	K13
GND	L1
GND	L10
GND	L11
GND	L12
GND	L13
GND	L22
GND	M1
GND	M10
GND	M11
GND	M12
GND	M13
GND	M22
GND	N10
GND	N11
GND	N12
GND	N13
GND	P14
GND	P9
GND	R15
GND	R8
GND	U16
GND	U6
GND	V18
GND	V5
GND	W19
GND	W4
GND	Y20
GND	Y3
GND/LP	G7
NC	A17
NC	A18

FG1152



Note

For Package Manufacturing and Environmental information, visit Resource center at http://www.microsemi.com/soc/products/rescenter/package/index.html.

FG1152	
AX2000 Function	**Pin Number**
IO51PB1F4	J20
IO52NB1F4	B20
IO52PB1F4	A20
IO53NB1F4	F20
IO53PB1F4	E20
IO54NB1F5	B21
IO54PB1F5	A21
IO55NB1F5	K21
IO55PB1F5	J21
IO56NB1F5	D21
IO56PB1F5	C21
IO57NB1F5	G22
IO57PB1F5	G21
IO58NB1F5	E22
IO58PB1F5	E21
IO59NB1F5	D22
IO59PB1F5	C22
IO60NB1F5	B23
IO60PB1F5	A23
IO61NB1F5	H22
IO61PB1F5	H21
IO62NB1F5	C24
IO62PB1F5	C23
IO63NB1F5	F23
IO63PB1F5	F22
IO64NB1F6	B24
IO64PB1F6	A24
IO65NB1F6	J22
IO65PB1F6	K22
IO66NB1F6	B25
IO66PB1F6	A25
IO67NB1F6	K23
IO67PB1F6	J23
IO68NB1F6	F24
IO68PB1F6	E24

FG1152	
AX2000 Function	**Pin Number**
IO69NB1F6	C27
IO69PB1F6	C26
IO70NB1F6	H24
IO70PB1F6	G24
IO71NB1F6	H23
IO71PB1F6	G23
IO72NB1F6	B28
IO72PB1F6	A28
IO73NB1F6	E26
IO73PB1F6	E25
IO74NB1F6	F26
IO74PB1F6	F25
IO75NB1F6	K25
IO75PB1F6	K24
IO76NB1F7	D27
IO76PB1F7	D26
IO77NB1F7	B29
IO77PB1F7	A29
IO78NB1F7	D28
IO78PB1F7	C28
IO79NB1F7	H25
IO79PB1F7	G25
IO80NB1F7	F27
IO80PB1F7	E27
IO81NB1F7	J25
IO81PB1F7	J24
IO82NB1F7	D29
IO82PB1F7	C29
IO83NB1F7	H26
IO83PB1F7	G26
IO84NB1F7	F28
IO84PB1F7	E28
IO85NB1F7	H27
IO85PB1F7	G27
Bank 2	

FG1152	
AX2000 Function	**Pin Number**
IO86NB2F8	J28
IO86PB2F8	J27
IO87NB2F8	M25
IO87PB2F8	L25
IO88NB2F8	L26
IO88PB2F8	K26
IO89NB2F8	G31
IO89PB2F8	F31
IO90NB2F8	H29
IO90PB2F8	G29
IO91NB2F8	K28
IO91PB2F8	K27
IO92NB2F8	J30
IO92PB2F8	H30
IO93NB2F8	L28
IO93PB2F8	L27
IO94NB2F8	K29
IO94PB2F8	J29
IO95NB2F8	K31
IO95PB2F8	J31
IO96NB2F9	J32
IO96PB2F9	H32
IO97NB2F9	M27
IO97PB2F9	M26
IO98NB2F9	L30
IO98PB2F9	K30
IO99NB2F9	N25
IO99PB2F9	N26
IO100NB2F9	M29
IO100PB2F9	L29
IO101NB2F9	L33
IO101PB2F9	L32
IO102NB2F9	K34
IO102PB2F9	K33
IO103NB2F9	N28

FG1152	
AX2000 Function	**Pin Number**
IO207PB4F19	AL20
IO208NB4F19	AG19
IO208PB4F19	AF19
IO209NB4F19	AN18
IO209PB4F19	AP18
IO210NB4F19	AE19
IO210PB4F19	AD19
IO211NB4F19	AL18
IO211PB4F19	AM18
IO212NB4F19/CLKEN	AJ20
IO212PB4F19/CLKEP	AK20
IO213NB4F19/CLKFN	AJ18
IO213PB4F19/CLKFP	AJ19
Bank 5	
IO214NB5F20/CLKGN	AJ16
IO214PB5F20/CLKGP	AJ17
IO215NB5F20/CLKHN	AJ15
IO215PB5F20/CLKHP	AK15
IO216NB5F20	AD16
IO216PB5F20	AE17
IO217NB5F20	AM17
IO217PB5F20	AL17
IO218NB5F20	AG16
IO218PB5F20	AF16
IO219NB5F20	AM16
IO219PB5F20	AL16
IO220NB5F20	AP16
IO220PB5F20	AN16
IO221NB5F20	AN15
IO221PB5F20	AP15
IO222NB5F20	AD15
IO222PB5F20	AE16
IO223NB5F21	AL14
IO223PB5F21	AL15
IO224NB5F21	AN14

FG1152	
AX2000 Function	**Pin Number**
IO224PB5F21	AP14
IO225NB5F21	AK13
IO225PB5F21	AK14
IO226NB5F21	AE15
IO226PB5F21	AF15
IO227NB5F21	AG14
IO227PB5F21	AG15
IO228NB5F21	AJ13
IO228PB5F21	AJ14
IO229NB5F21	AM13
IO229PB5F21	AM14
IO230NB5F21	AE14
IO230PB5F21	AF14
IO231NB5F21	AN12
IO231PB5F21	AP12
IO232NB5F21	AG13
IO232PB5F21	AH13
IO233NB5F21	AL12
IO233PB5F21	AL13
IO234NB5F21	AE13
IO234PB5F21	AF13
IO235NB5F22	AN11
IO235PB5F22	AP11
IO236NB5F22	AM11
IO236PB5F22	AM12
IO237NB5F22	AJ11
IO237PB5F22	AJ12
IO238NB5F22	AH11
IO238PB5F22	AH12
IO239NB5F22	AK10
IO239PB5F22	AK11
IO240NB5F22	AE12
IO240PB5F22	AF12
IO241NB5F22	AN10
IO241PB5F22	AP10

FG1152	
AX2000 Function	**Pin Number**
IO242NB5F22	AG11
IO242PB5F22	AG12
IO243NB5F22	AL9
IO243PB5F22	AL10
IO244NB5F22	AM8
IO244PB5F22	AM9
IO245NB5F23	AH10
IO245PB5F23	AJ10
IO246NB5F23	AF10
IO246PB5F23	AF11
IO247NB5F23	AJ9
IO247PB5F23	AK9
IO248NB5F23	AN7
IO248PB5F23	AP7
IO249NB5F23	AL7
IO249PB5F23	AL8
IO250NB5F23	AE10
IO250PB5F23	AE11
IO251NB5F23	AK8
IO251PB5F23	AJ8
IO252NB5F23	AH8
IO252PB5F23	AH9
IO253NB5F23	AN6
IO253PB5F23	AP6
IO254NB5F23	AG9
IO254PB5F23	AG10
IO255NB5F23	AJ7
IO255PB5F23	AK7
IO256NB5F23	AL6
IO256PB5F23	AM6
Bank 6	
IO257NB6F24	AG6
IO257PB6F24	AH6
IO258NB6F24	AD9
IO258PB6F24	AE9

CQ352	
AX1000 Function	Pin Number
Bank 0	
IO02NB0F0	341
IO02PB0F0	342
IO03PB0F0	343
IO04NB0F0	337
IO04PB0F0	338
IO08NB0F0	331
IO08PB0F0	332
IO09NB0F0	335
IO09PB0F0	336
IO24NB0F2	325
IO24PB0F2	326
IO25NB0F2	323
IO25PB0F2	324
IO30NB0F2/HCLKAN	319
IO30PB0F2/HCLKAP	320
IO31NB0F2/HCLKBN	313
IO31PB0F2/HCLKBP	314
Bank 1	
IO32NB1F3/HCLKCN	305
IO32PB1F3/HCLKCP	306
IO33NB1F3/HCLKDN	299
IO33PB1F3/HCLKDP	300
IO38NB1F3	295
IO38PB1F3	296
IO54NB1F5	287
IO54PB1F5	288
IO55NB1F5	289
IO55PB1F5	290
IO56NB1F5	281
IO56PB1F5	282
IO57NB1F5	283
IO57PB1F5	284
IO59NB1F5	277
IO59PB1F5	278

CQ352	
AX1000 Function	Pin Number
IO60NB1F5	275
IO60PB1F5	276
IO61NB1F5	271
IO61PB1F5	272
IO63NB1F5	269
IO63PB1F5	270
Bank 2	
IO64NB2F6	259
IO64PB2F6	260
IO67NB2F6	261
IO67PB2F6	262
IO68NB2F6	255
IO68PB2F6	256
IO69NB2F6	253
IO69PB2F6	254
IO74NB2F7	249
IO74PB2F7	250
IO75NB2F7	247
IO75PB2F7	248
IO76NB2F7	243
IO76PB2F7	244
IO77NB2F7	241
IO77PB2F7	242
IO78NB2F7	237
IO78PB2F7	238
IO79NB2F7	235
IO79PB2F7	236
IO82NB2F7	231
IO82PB2F7	232
IO83NB2F7	229
IO83PB2F7	230
IO94NB2F8	225
IO94PB2F8	226
IO95NB2F8	223
IO95PB2F8	224

CQ352	
AX1000 Function	Pin Number
Bank 3	
IO96NB3F9	217
IO96PB3F9	218
IO97NB3F9	219
IO97PB3F9	220
IO99NB3F9	213
IO99PB3F9	214
IO108NB3F10	211
IO108PB3F10	212
IO109NB3F10	207
IO109PB3F10	208
IO111NB3F10	205
IO111PB3F10	206
IO112NB3F10	199
IO112PB3F10	200
IO113NB3F10	201
IO113PB3F10	202
IO115NB3F10	195
IO115PB3F10	196
IO116NB3F10	193
IO116PB3F10	194
IO117NB3F10	189
IO117PB3F10	190
IO124NB3F11	183
IO124PB3F11	184
IO125NB3F11	187
IO125PB3F11	188
IO127NB3F11	181
IO127PB3F11	182
IO128NB3F11	179
IO128PB3F11	180
Bank 4	
IO130NB4F12	172
IO130PB4F12	173
IO131NB4F12	170

Revision	Changes	Page
Revision 12 (v2.4)	Revised ordering information and timing data to reflect phase out of –3 speed grade options.	
	Table 2-3 was updated.	2
Revision 11 (v2.3)	The "Packaging Data" section is new.	iv
	Table 2-2 was updated.	2-1
	"VCCDA Supply Voltage" was updated.	2-9
	"PRA/B/C/D Probe A, B, C and D" was updated.	2-10
	The "User I/Os" was updated.	2-11
Revision 10 (v2.2)	Figure 1-3 was updated.	1-2
	Table 2-2 was updated.	2-1
	The "Power-Up/Down Sequence" section was updated.	2-1
	Table 2-4 was updated.	2-3
	Table 2-5 was updated.	2-4
	The "Timing Characteristics" section was added.	2-7
	Table 2-7 was updated.	2-7
	Figure 2-1 was updated.	2-8
	The External Setup and Clock-to-Out (Pad-to-Pad) equations in the "Hardwired Clock – Using LVTTL 24 mA High Slew Clock I/O" section were updated.	2-8
	The External Setup and Clock-to-Out (Pad-to-Pad) in the "Routed Clock – Using LVTTL 24 mA High Slew Clock I/O" section were updated.	2-8
	The "Global Pins" section was updated.	2-10
	The "User I/Os" section was updated.	2-11
	Table 2-17 was updated.	2-19
	Figure 2-8 was updated.	2-20
	Figure 2-13 and Figure 2-14 were updated.	2-24
	The following timing parameters were renamed in I/O timing characteristic tables from Table 2-22 to Table 2-60: $t_{IOCLKQ} > t_{ICLKQ}$ $t_{IOCLKY} > t_{OCLKQ}$	2-26 to 2-52
	Timing numbers were updated from Table 2-22 to Table 2-78.	2-26 to 2-69
	The "R-Cell" section was updated.	2-58
	Figure 2-59 was updated.	2-89
	Figure 2-60 was updated.	2-89
	Figure 2-67 was updated.	2-100
	Figure 2-68 was updated.	2-101
	Table 2-89 to Table 2-93 were updated.	2-90 to 2-94
	Table 2-98 to Table 2-102 were updated.	2-102 to 2-106